

Title (en)  
Electrodeposition medium

Title (de)  
Mittel zur Elektrobeschichtung

Title (fr)  
Milieu d'électrodéposition

Publication  
**EP 1369502 A1 20031210 (EN)**

Application  
**EP 03076855 A 19980130**

Priority  

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- US 3602497 P 19970131
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Abstract (en)  
The present invention relates to a cathodic electrodeposition medium for forming a deposit on the surface of a metallic or conductive surface. The medium comprises a combination of water, silica, at least one water soluble silicate, and at least one water soluble dopant wherein the medium has a basic pH. The resulting deposit imparts improved corrosion resistance to the underlying substrate. In the preferred embodiment, the medium comprises sodium silicate and has a pH of greater than approximately 10. <IMAGE>

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**C25D 9/04**

IPC 8 full level  
**C25D 9/04** (2006.01)

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Citation (search report)  

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